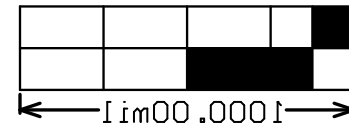
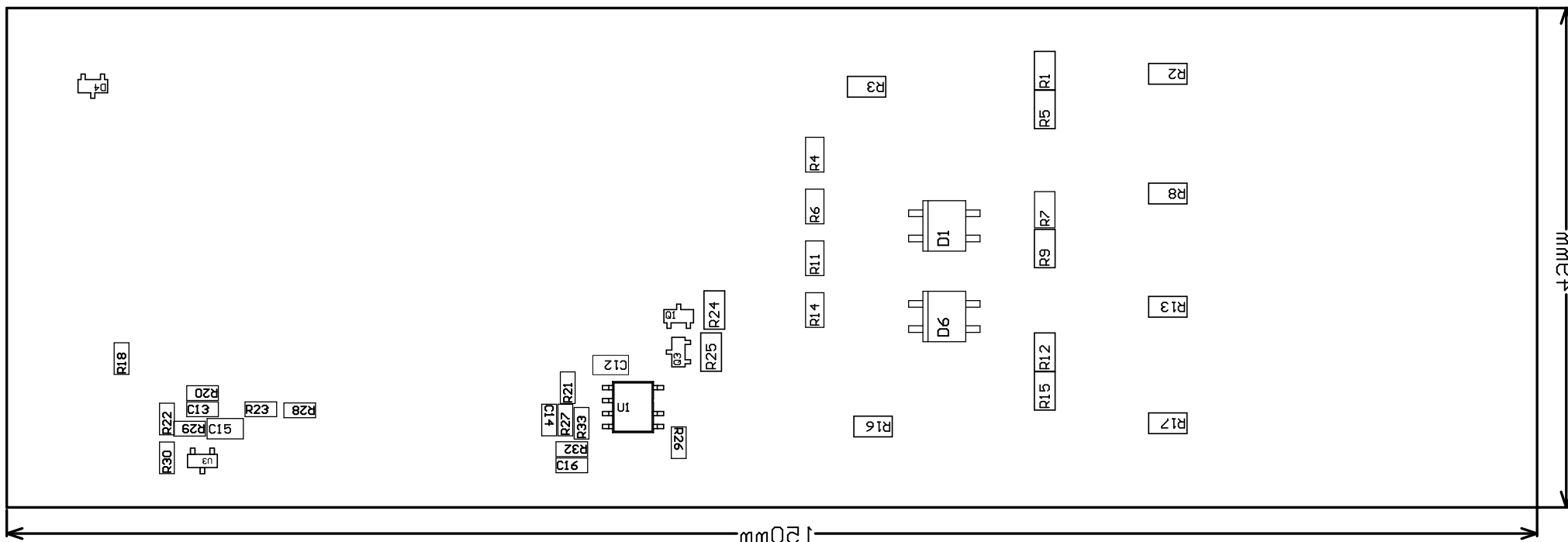


COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.  
 ASSEMBLY VARIANT: [No Variations]

PCB VIEWED FROM TOP SIDE	BOARD #: PMP30164	REV: E1	SUN REV: Not In VersionControl
M2 Board Dimensions	TID #: ChangeMe!		
PLOT NAME = Assembly Top	GENERATED : 11/17/2016 3:00:58 PM		TEXAS INSTRUMENTS



PCB VIEWED FROM BOTTOM SIDE	BOARD #: PMP30164	REV: E1	SUN REV: Not In VersionControl
	TID #: ChangeMe!	MS Board Numbers are our business	
PLOT NAME = Assembly Bottom	GENERATED : 11/17/2016 3:00:58 PM	TEXAS INSTRUMENTS	

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